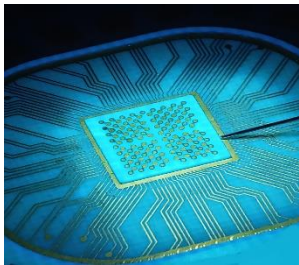




News Release

January 2022

Light Cured - PCB Assembly Adhesives



epoxySet introduces an extended line of light cured adhesives specifically designed for dam and fill applications. These cutting edge adhesives are useable for chip encapsulation, smart card fabrication and other state-of-the-art electronic assembly requirements. These systems will increase performance, decrease processing time and eliminate failures.

UV-5400LV - a low viscosity, low CTE adhesive for fill operation that will offer high strength to all PCB materials.

UV-8300T - a thixotropic, damming material with very low CTE.

UV 5403S is a slightly thixotropic material that can be injected as a fill adhesive, used as damming material or as a glob top.

All these advanced polymers are low ion /high purity and halogen free as well as REACH & RoHS compliant. They are all specifically formulated to cure in 10 seconds with a bond line intensity of 250mW/cm², 365nm LED energy source. Of course, they will cure just as quickly with D or H style UV lights. They can also be gelled at lower intensities and then heat post cured for manufacturing flexibility. These systems pass 1000 hours at 85%RH/85°C and offer continuous operation at 150°C.

epoxySet is an innovative custom formulator of Epoxies, Urethanes, Silicones, Thermal Greases and UV cures for the electronic, medical, semi-conductor, optics, automotive and aerospace industries. Our extensive experience allows us to quickly modify our wide-ranging product line for any requirement. Please contact our technical support staff at 401-726-4500 or info@epoxyset.com

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